



# S1170G

(UL ANSI: FR-15.1) High Tg, Halogen-free

## FEATURES

- Anti-CAF capability
- Lead-free compatible
- Excellent through-hole reliability
- Halogen, antimony and red phosphorous free

## APPLICATIONS

Computer  
Instrument  
Smartphone  
Consumer electronics  
Automotive electronics

## GENERAL PROPERTIES

Test Items	Test Method	Test Condition	Unit	Typical Value	
Tg	IPC-TM-650 2.4.25D	DSC	°C	175	
	IPC-TM-650 2.4.24.4	DMA	°C	180	
Td	IPC-TM-650 2.4.24.6	TGA (5% W.L)	°C	390	
T288	IPC-TM-650 2.4.24.1	TMA	min	60	
T260	IPC-TM-650 2.4.24.1	TMA	min	>60	
Thermal Stress	IPC-TM-650 2.4.13.1	288°C, solder dip	s	>100	
CTE (Z-axis)	IPC-TM-650 2.4.24	Before Tg	ppm/°C	45	
	IPC-TM-650 2.4.24	After Tg	ppm/°C	210	
	IPC-TM-650 2.4.24	50-260°C	%	2.3	
Permittivity (1GHz)	IPC-TM-650 2.5.5.9	C-24/23/50	-	4.4	
Loss Tangent (1GHz)	IPC-TM-650 2.5.5.9	C-24/23/50	-	0.010	
Volume Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	MΩ-cm	5.65×10 <sup>7</sup>	
Surface Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	MΩ	5.99×10 <sup>6</sup>	
Arc Resistance	IPC-TM-650 2.5.1	D-48/50+D-0.5/23	s	180	
Dielectric Breakdown	IPC-TM-650 2.5.6	D-48/50+D-0.5/23	kV	>45	
Peel Strength (1oz)	IPC-TM-650 2.4.8	288°C/10s	N/mm [lb/in]	1.3 [7.43]	
Flexural Strength (LW/CW)	IPC-TM-650 2.4.4	A	Mpa	550/450	
Water Absorption	IPC-TM-650 2.6.2.1	D-24/23	%	0.12	
Flammability	UL94	C-48/23/50	Rating	V-0	
Halogen Content	Br	EN 14582	A	ppm	≤900
	Cl				≤900
	Br+Cl				≤1500

Remarks: 1. Specification sheet: IPC-4101/130, is for your reference only.  
2. All the typical value is based on the 1.6mm (8\*7628) specimen.  
3. All the typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd for detailed information, and all rights from this data sheet are reserved by Shengyi Technology Co., Ltd.

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# S1170GB PREPREG

(UL ANSI: FR-15.1) Bonding Prepreg For S1170G

## PREPREG PARAMETERS

Glass fabric type	Resin content (%)	Cured thickness (mm)	Standard size (Roll type)
106	72	0.053	1.260m×150m
	76	0.064	
1080	64	0.078	1.260m×300m
	68	0.090	
2313	55	0.101	
	59	0.114	
2116	52	0.119	1.260m×250m
	55	0.130	
	58	0.141	
1506	45	0.159	1.260m×150m
	48	0.171	
7628	43	0.193	
	46	0.207	
	48	0.218	
	50	0.229	

Other type, resin content and size could be available upon request.

## HOT PRESSING CYCLE

- The heat-up rate depends on the inner copper or the structure of multilayer PCB.
- Curing time: >60min (190~200℃).
- If you need any more detail information, please turn to Shengyi Technology Co., Ltd.

## STORAGE CONDITION

- 3 months when stored at < 23℃ and <50% RH.
- 6 months when stored at <5℃. Normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Keeping in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.

## PURCHASING INFORMATION

Thickness	Copper foil	Standard size
0.05mm to 3.2mm	12um to 105 um	1,020mm×1,220mm(40"×48") 915mm×1,220mm(36"×48")
		1,070mm×1,220mm(42"×48")

Remarks: Other sheet size and thickness could be available upon request.

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